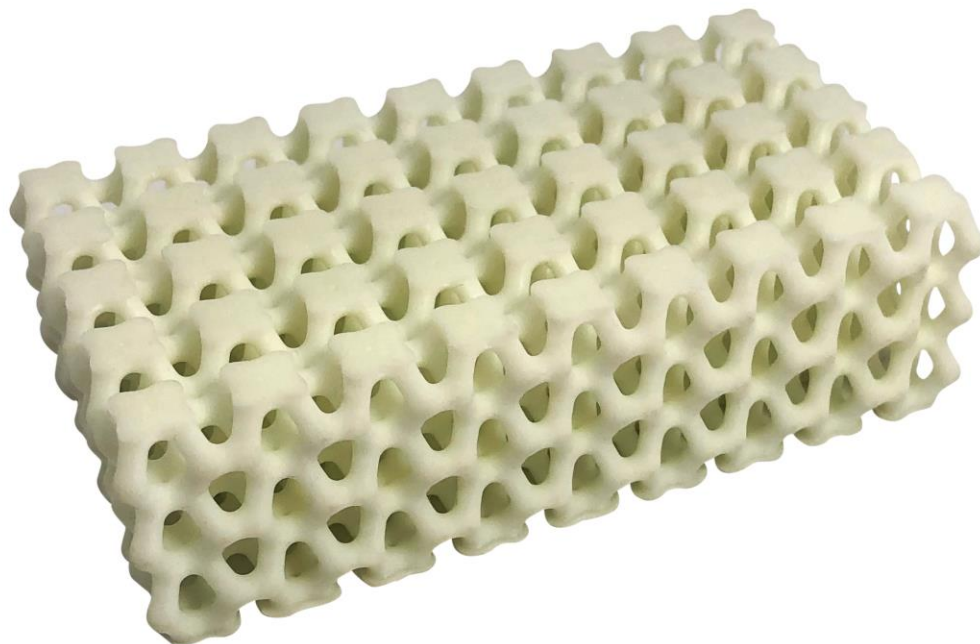


LOCTITE®



LOCTITE 3D IND475™

A60 High Rebound

Photoelastic

White, Black

LOCTITE®

Henkel Corporation

loctite3dp@henkel.com





IND475™

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LOCTITE 3D IND475™

LOCTITE 3D IND475 is a single component UV resin that cures to a soft, elastomeric material.

LOCTITE 3D IND475 is a flexible material that gives a good balance of hardness, strength and elongation.

LOCTITE 3D IND475 is a low viscosity liquid, printable at room temperature across various DLP platforms.



Benefits:

- True elastomeric behavior
- Fast Printing with low shrinkage behavior
- High resilience / High energy return



Ideal for:

- Air and dust gaskets
- Flexible seals and housings
- Cushioning pads



Markets:



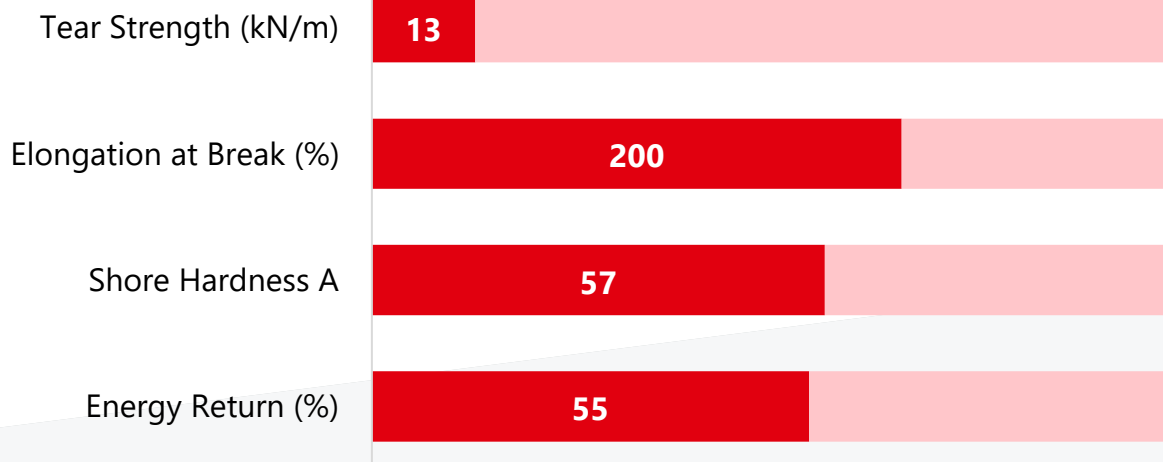
Industry



Automotive



Consumer
Goods

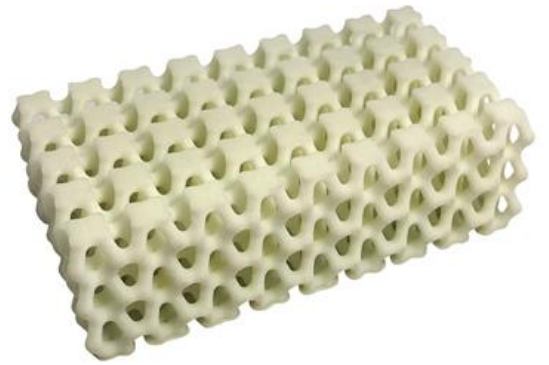


**Values shown are linked to LOCTITE IND475 White as reference, please refer to the specific mechanical properties for each of the colors shown in this document*





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PROPERTIES

Mechanical Properties	Measure	Method	Green	Post Processed
Tensile Stress at Break	MPa	ASTM D638	-	3.1 ± 0.3 [1]
Young's Modulus	MPa	ASTM D638	-	1.1 ± 0.5 [1]
Elongation at Break	%	ASTM D638	-	201 ± 16 [1]
Tear Strength	kN/m	ASTM D624	-	12.6 ± 0.6 [2]
Energy Return	%	Internal	-	55 [3]
Other Properties				
Shore Hardness (5s)	A	ASTM D2240	-	57 [4]
Solid Density (Green)	g/cm ³	ASTM D792	-	1.43 [5]
Solid Density (Cured)	g/cm ³	ASTM D792	-	1.04 [5]
Volumetric Shrinkage	%	Internal	-	-27 [5]
Water Absorption (24hr)	%	ASTM D570	-	2.1 ± 0.1 [6]
Water Absorption (72hr)	%	ASTM D570	-	4.5 ± 0.1 [6]
Water Absorption (168hr)	%	ASTM D570	-	6.5 ± 0.1 [6]
Compression Set	%	D395, 22hr	-	28.7 [9]
Biocompatibility				
Irritation		ISO 10993-23*		Comply ^[8]

Liquid Properties	Measure	Method	Value
Viscosity @ 25°C (77°F)	cP	ASTM D7867	1,400 [7]
Liquid Density	g/cm ³	ASTM D1475	1.02 [5]

*All specimen are printed unless otherwise noted. All specimen were conditioned in ambient lab conditions at 19-23°C / 40-60% RH for at least 24 hours." ASTM Methods: D638 Type IV, 50 mm/min, D790-B, 2 mm/min, D648, D256 Notched IZOD (Machine Notched), 6 mm x 12 mm, D570 0.125" x 2" Disc 24hr@ 25°C, D2240, Type "D" (0, 3 seconds), D7867, D1475

*The biological assessment has been performed based on the in vitro method according to ISO10993-23

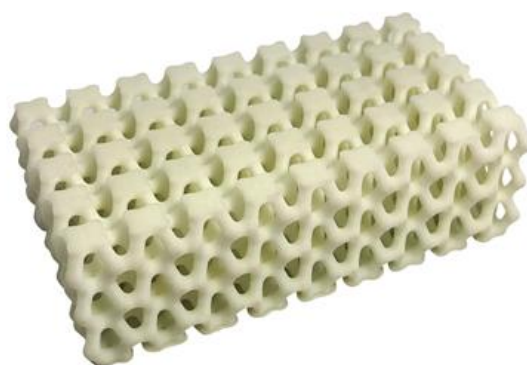
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PROPERTIES

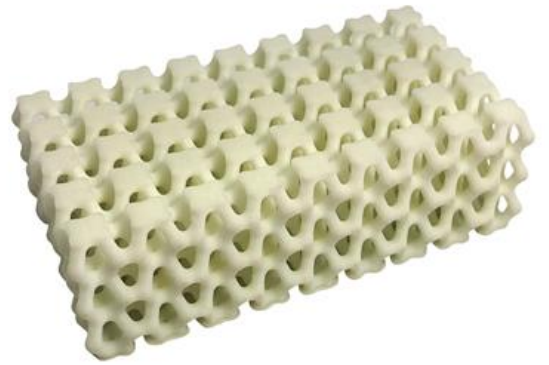
Electrical Properties	Measure	Method	Green	Post Processed
Volume Resistivity	$\Omega\cdot\text{cm}$	ASTM D257	-	8.95E +11 [1]
Surface Resistivity	Ω	ASTM D257	-	2.53E +13 [1]
Dielectric Strength	kV/mm	ASTM D149	-	29.6 [2]
AC Relative Permittivity (Dielectric Constant) ^[3]				
at 50 Hz (XY)	none	ASTM D150	-	5.1
at 1 kHz (XY)	none	ASTM D150	-	4.6
at 1 MHz (XY)	none	ASTM D150	-	4.3
AC Loss Characteristic (Dissipation Factor) ^[3]				
at 50 Hz (XY)	none	ASTM D150	-	0.061
at 1 kHz (XY)	none	ASTM D150	-	0.070
at 1 MHz (XY)	none	ASTM D150	-	0.107

Internal Data Sources:
[1] FOR106280 [2] FOR106282 [3] FOR106281





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WORKFLOW

Validated workflows need to be followed to achieve properties as provided in the TDS. Examples of validated workflow steps are listed below. Users should defer to the most current workflow information for best results which can be found at <https://www.loctiteam.com/printer-validation-settings>

PRINTER SETTINGS

LOCTITE 3D IND475 WH is formulated to print optimally on industrial DLP printer. Read the safety data sheet carefully to get details about health and safety instructions. Recommended print parameters:

- Shake resin bottle well before usage
- Temperature: 20°C to 30°C
- Intensity: 3 mW/cm² to 10 mW/cm²

Exposure time for an intensity of 5 mW/cm²

Layer Thickness (µm):	100	Ec (mJ/cm ²)	3.55
First layer time (s)	60	Dp (mm):	0.13
Burn in region (s):	35	Model Layer Exposure (s):	3.5

CLEANING

LOCTITE 3D IND475 WH requires post processing to achieve specified properties. Prior to post curing, support structures should be removed from the printed part, and the part should then be washed. Use compressed air to remove residual solvent from the surface of the material between intervals.

Post Process Step	Agent	Method	Duration	Interval	Additional Info
Cleaning #1	LOCTITE Cleaner T	Sonic	2 min	1	Alternative: TPM
Cleaning #2	IPA	Sonic	2 min	1	Use fresh IPA
Dry	n.a.	Compressed air	30 s	1	Air pressure (30 psi)
Wait before post curing	n.a.	Ambient	60 min	1	Room temperature





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WORKFLOW

Validated workflows need to be followed to achieve properties as provided in the TDS. Examples of validated workflow steps are listed below. Users should defer to the most current workflow information for best results which can be found at <https://www.loctiteam.com/printer-validation-settings>

POST CURING

LOCTITE 3D IND475 WH requires **post curing in water** to achieve specified properties. It is recommended to apply a mold release on the parts before submerged in a transparent water container.

UV Curing Unit	UV Source	Intensity	Cure time Per side	Additional Settings (Shelf, Output Energy)
Loctite UVALOC 1000	Mercury Arc Bulb (broad spectrum)	30 mW/cm ² at 365nm	5 min	500 W, 3 rd shelf from the top
Dymax 5000 EC Flood	Mercury Arc Bulb (broad spectrum)	150 - 175 mW/cm ² at 380nm	10 min	400W, Shelf K
Loctite CL36	405nm LED	80 mW/cm ² at 405 nm	90 min	100% top & side

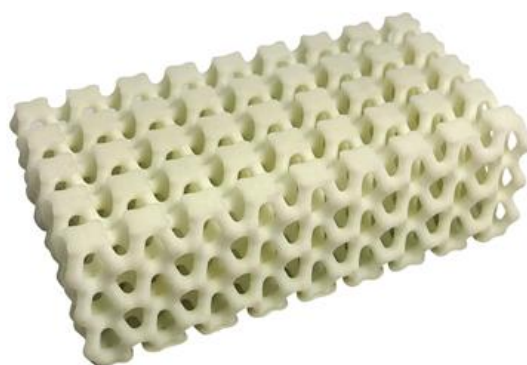
STORAGE

Store **LOCTITE 3D IND475 WH** in the unopened container in a dry location. Optimal Storage: 8°C to 30°. Storage below 8°C or above 30°C can adversely affect product properties. Material removed from containers may be contaminated during use. For this reason, filter used resin with 190µm mesh filter before placing back into proper storage container.





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PROPERTIES

Mechanical Properties	Measure	Method	Green	Post Processed
Tensile Stress at Break	MPa	ASTM D638	-	2.4 ± 0.6 [1]
Young's Modulus	MPa	ASTM D638	-	2.5 ± 0.3 [1]
Elongation at Break	%	ASTM D638	-	122 ± 11 [1]
Tear Strength	kN/m	ASTM D624	-	7.5 ± 1.2 [2]
Energy Return	%	Internal	-	77 ± 4 [3]
Other Properties				
Shore Hardness (5s)	A	ASTM D2240	-	45 [4]
Solid Density (Green)	g/cm ³	ASTM D792	-	1.16 [5]
Solid Density (Cured)	g/cm ³	ASTM D792	-	1.06 [5]
Volumetric Shrinkage	%	Internal	-	-9 [5]
Water Absorption (24hr)	%	ASTM D570	-	3.2 [6]
Water Absorption (72hr)	%	ASTM D570	-	5.4 [6]
Water Absorption (168hr)	%	ASTM D570	-	8.5 [6]
Compression Set	%	D395, 22hr	-	25.4 [8]

Liquid Properties	Measure	Method	Value
Viscosity @ 25°C (77°F)	cP	ASTM D7867	1,500 [7]
Liquid Density	g/cm ³	ASTM D1475	1.01 [5]

All specimen are printed unless otherwise noted. All specimen were conditioned in ambient lab conditions at 19-23°C / 40-60% RH for at least 24 hours. ASTM Methods: D638 Type IV, 5 mm/min, D790-B, 2 mm/min, D648, D256 Notched IZOD (Machine Notched), 6 mm x 12 mm, D570 0.125" x 2" Disc 24hr@ 25°C, D2240, Type "D" (0, 3 seconds), D7867, D1475

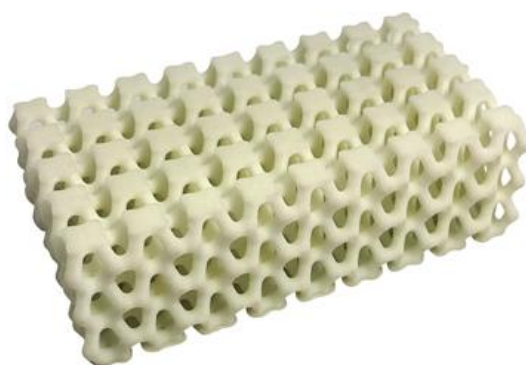
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[1] FOR40695, [2] FOR40696, [3] FOR40697, [4] FOR40692, [5] FOR35576, [6] FOR29248, [7] FOR40548, [8] FOR167730





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PROPERTIES

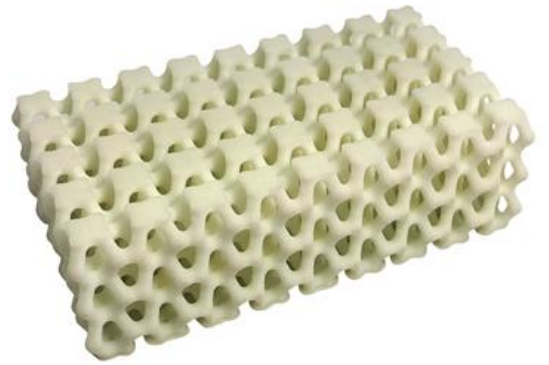
Electrical Properties	Measure	Method	Green	Post Processed
Volume Resistivity	$\Omega\text{-cm}$	ASTM D257	-	5.79E +10 ^[1]
Surface Resistivity	Ω	ASTM D257	-	1.43E +12 ^[1]
Dielectric Strength	kV/mm	ASTM D149	-	27.9 ^[2]
AC Relative Permittivity (Dielectric Constant) ^[3]				
at 50 Hz (XY)	none	ASTM D150	-	7.2
at 1 kHz (XY)	none	ASTM D150	-	5.7
at 1 MHz (XY)	none	ASTM D150	-	4.2
AC Loss Characteristic (Dissipation Factor) ^[3]				
at 50 Hz (XY)	none	ASTM D150	-	0.067
at 1 kHz (XY)	none	ASTM D150	-	0.090
at 1 MHz (XY)	none	ASTM D150	-	0.193

Internal Data Sources:
[1] FOR106283 [2] FOR106286 [3] FOR106285





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WORKFLOW

Validated workflows need to be followed to achieve properties as provided in the TDS. Examples of validated workflow steps are listed below. Users should defer to the most current workflow information for best results which can be found at <https://www.loctiteam.com/printer-validation-settings>

PRINTER SETTINGS

LOCTITE 3D IND475 BK is formulated to print optimally on industrial DLP printer. Read the safety data sheet carefully to get details about health and safety instructions. Recommended print parameters:

- Shake resin bottle well before usage
- Temperature: 20°C to 30°C
- Intensity: 3 mW/cm² to 10 mW/cm²

Exposure time for an intensity of 3 mW/cm²

Layer Thickness (µm):	100	Ec (mJ/cm ²)	
First layer time (s)	60	Dp (mm):	
Burn in region (s):	35	Model Layer Exposure (s):	4.7

CLEANING

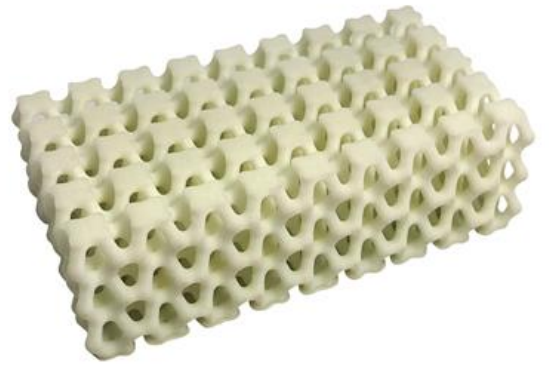
LOCTITE 3D IND475 BK requires post processing to achieve specified properties. Prior to post curing, support structures should be removed from the printed part, and the part should then be washed. Use compressed air to remove residual solvent from the surface of the material between intervals.

Post Process Step	Agent	Method	Duration	Interval	Additional Info
Cleaning #1	LOCTITE Cleaner T	Sonic	2 min	1	Alternative: TPM
Cleaning #2	IPA	Sonic	2 min	1	Use fresh IPA
Dry	n.a.	Compressed air	30 s	1	Air pressure (30 psi)
Wait before post curing	n.a.	Ambient	60 min	1	Room temperature





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WORKFLOW

Validated workflows need to be followed to achieve properties as provided in the TDS. Examples of validated workflow steps are listed below. Users should defer to the most current workflow information for best results which can be found at <https://www.loctiteam.com/printer-validation-settings>

POST CURING

LOCTITE 3D IND475 BK requires **post curing in water** to achieve specified properties. It is recommended to apply a mold release on the parts before submerged in a transparent water container.

UC Curing Unit	UV Source	Intensity	Cure time Per side	Additional Settings (Shelf, Output Energy)
Loctite UVALOC 1000	Mercury Arc Bulb (broad spectrum)	30 mW/cm ² at 365 nm	10 min	500 W, 3 rd shelf from the top
Dymax 5000 EC Flood	Mercury Arc Bulb (broad spectrum)	150 - 175 mW/cm ² at 380 nm	10 min	400W, Shelf I
Nexa Cure	365nm and 405nm LED	20-25mW/cm ²	60 min	Middle shelf

STORAGE

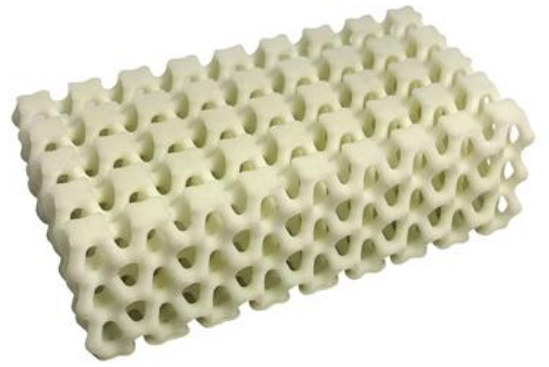
Store **LOCTITE 3D IND475 BK** in the unopened container in a dry location. Optimal Storage: 8°C to 30°. Storage below 8°C or above 30°C can adversely affect product properties. Material removed from containers may be contaminated during use. For this reason, filter used resin with 190µm mesh filter before placing back into proper storage container.





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Additional Workflow Notes

Printing with **LOCTITE® 3D IND475™** requires detailed attention to interactions between the material and the hardware in use. Mechanical process settings must be optimized for each printer based on the hardware and software capabilities. Due to the low durometer and high elasticity of the material, printed parts may sway during tray release, build head movement, and upon re-entering the resin. For this reason, the user must consider many variables while printing. Some applicable print process considerations and respective guidelines are discussed below. Critical considerations include adhesion behavior at the print interface, model geometry, and model print orientation.

Lift Height Between Layers: Larger parts may require larger lift heights due to overall elongation magnitude.

- Small parts (<25 mm height): 10-15mm
- Medium parts (25 - 100 mm height): 20-25 mm
- Large parts (>100mm height): 25-30 mm

Build Head Movement Rates: Thicker parts allow for more rapid rates due to overall part rigidity compared to printing forces.

- Low Thickness (<5mm thickness): 3-5 mm/second
- Medium Thickness (5-10 mm thickness): 3-10 mm/second
- High Thickness (>10 mm thickness): 3-20 mm/second

Time Delay Before Layer Exposure:

- Generally, 3-5 seconds is sufficient due to the resin's low viscosity. Parts with thin features may require longer times for the small features to return to the correct position as they normalize with the resin's viscosity forces.

Support Structures:

- Place supports on non-critical model surfaces if possible. Support structure placement and geometry is model-dependent based on model layer surface area. General recommendations are provided.
- Support Thickness: 0.6-0.8 mm diameter
- Support Contact Area: 25-75% support thickness

POST PROCESSING

- **LOCTITE® 3D IND475™** requires post processing to achieve specified properties. Prior to post curing, the part should be washed in a friendly cleaner. We recommend in **LOCTITE® Cleaner T**.
- Post curing of **LOCTITE® 3D IND475™** to reach stated property targets must be cured in water or an alternative inert medium.
- Coating parts with a spray-on mold release agent such as **LOCTITE® Frekote 770-NC** or **Smooth-On Universal Mold Release** prior to post curing can reduce the surface tack of a final part. After curing, the mold release can be rinsed off with water or Isopropanol.



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NOTE

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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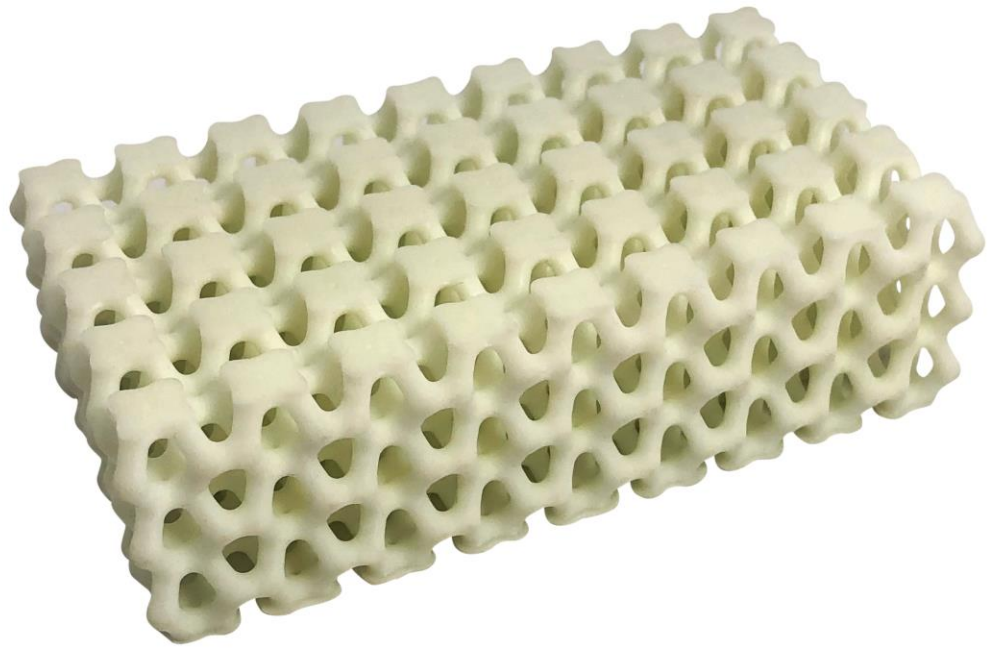
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